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- The diagram illustrates the cross-section of a 4-layer PCB. From top to bottom, the layers are:
 - TOP** (Surface)
 - LAYER 1**: Copper Foil 0.5oz / Plate to 1.0oz min Layer 1
 - FR-370HR**: Pre-preg 0.0097" (material)
 - LAYER 2**: Core 0.0358" 1.0oz / 1.0oz Layer 2 & 3
 - FR-370HR**: Pre-preg 0.0097" (material)
 - LAYER 3**: Core 0.0358" 1.0oz / 1.0oz Layer 2 & 3
 - FR-370HR**: Pre-preg 0.0097" (material)
 - LAYER 4**: Copper Foil 0.5oz / Plate to 1.0oz min Layer 4
 - BOTTOM** (Surface)
 The diagram shows the alternating layers of prepreg, core, and copper foil, with the core being 0.0358" thick and the prepreg being 0.0097" thick. The copper foil is 0.5oz thick, and the plating is 1.0oz min thick.

DO NOT SCALE DRAWING

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